

Abstract**Method and apparatus for trimming the working layers of a
double-side grinding apparatus**

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The invention relates to a method and a trimming apparatus for trimming two working layers which contain bonded abrasive and are applied on the mutually facing sides of an upper and of a lower working disk of a grinding apparatus for the simultaneous
10 double-side processing of flat workpieces, by means of at least one trimming apparatus, comprising a trimming disk, a plurality of trimming bodies and an outer tothing, wherein the at least one trimming apparatus is moved between the rotating working disks by means of a rolling apparatus and the outer tothing
15 under pressure and with addition of a cooling lubricant, which contains no substances with abrasive action, on cycloidal paths relative to the working layers, wherein the trimming bodies release abrasive substances upon contact with the working layers and thus effect material removal from the working layers
20 by means of loose grain. A plurality of measures for improving this method are implemented:

The trimming bodies are arranged within a ring-shaped region having a defined width on the trimming disk. The outer tothing
25 of the trimming disk is height-adjustable relative to the trimming disk. The direction of rotation of all the drives of the grinding apparatus is changed at least twice during the trimming or dressing. Depending on the previously measured shape profile of the two working layers, the material removal
30 from the lower and the upper working layer can be varied independently of one another.

Fig. 3D